

## Dual Binary to 1-of-4 Decoder/Demultiplexer

The MC14555B and MC14556B are constructed with complementary MOS (CMOS) enhancement mode devices. Each Decoder/Demultiplexer has two select inputs (A and B), an active low Enable input (E), and four mutually exclusive outputs (Q0, Q1, Q2, Q3). The MC14555B has the selected output go to the "high" state, and the MC14556B has the selected output go to the "low" state. Expanded decoding such as binary-to-hexadecimal (1-of-16), etc., can be achieved by using other MC14555B or MC14556B devices.

Applications include code conversion, address decoding, memory selection control, and demultiplexing (using the Enable input as a data input) in digital data transmission systems.

- Diode Protection on All Inputs
- Active High or Active Low Outputs
- Expandable
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- All Outputs Buffered
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range

### MAXIMUM RATINGS\* (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage	- 0.5 to + 18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage (DC or Transient)	- 0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient), per Pin	± 10	mA
P <sub>D</sub>	Power Dissipation, per Package†	500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
T <sub>L</sub>	Lead Temperature (8-Second Soldering)	260	°C

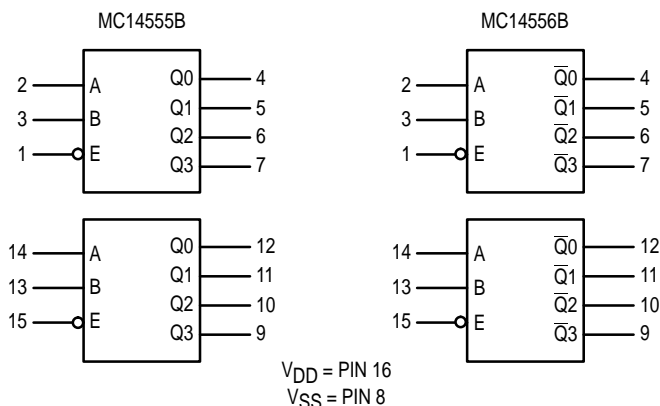
\* Maximum Ratings are those values beyond which damage to the device may occur.

† Temperature Derating:

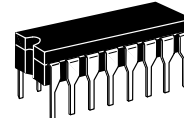
"P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C Ceramic

"L" Packages: - 12 mW/°C From 100°C To 125°C

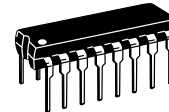
### BLOCK DIAGRAM



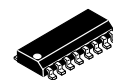
## MC14555B MC14556B



**L SUFFIX**  
CERAMIC  
CASE 620



**P SUFFIX**  
PLASTIC  
CASE 648



**D SUFFIX**  
SOIC  
CASE 751B

### ORDERING INFORMATION

MC14XXXBCP	Plastic
MC14XXXBCL	Ceramic
MC14XXXBD	SOIC

T<sub>A</sub> = - 55° to 125°C for all packages.

### TRUTH TABLE

Inputs			Outputs								
Enable	Select		MC14555B				MC14556B				
	E	B	A	Q3	Q2	Q1	Q0	Q3	Q2	Q1	Q0
0	0	0	0	0	0	1	1	1	1	1	0
0	0	1	0	0	1	0	1	1	1	0	1
0	1	0	0	1	0	0	1	0	1	1	1
0	1	1	1	0	0	0	0	0	1	1	1
1	X	X	0	0	0	0	1	1	1	1	1

X = Don't Care

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>in</sub> and V<sub>out</sub> should be constrained to the range V<sub>SS</sub> ≤ (V<sub>in</sub> or V<sub>out</sub>) ≤ V<sub>DD</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.

**ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>DD</sub> Vdc	- 55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ #	Max	Min	Max		
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level V <sub>OL</sub>	5.0	—	0.05	—	0	0.05	—	0.05	Vdc	
		10	—	0.05	—	0	0.05	—	0.05		
15		—	0.05	—	0	0.05	—	0.05			
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level V <sub>OH</sub>	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc	
		10	9.95	—	9.95	10	—	9.95	—		
		15	14.95	—	14.95	15	—	14.95	—		
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level V <sub>IL</sub>	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc	
		10	—	3.0	—	4.50	3.0	—	3.0		
		15	—	4.0	—	6.75	4.0	—	4.0		
	"1" Level (V <sub>O</sub> = 0.5 or 4.5 Vdc) (V <sub>O</sub> = 1.0 or 9.0 Vdc) (V <sub>O</sub> = 1.5 or 13.5 Vdc)	V <sub>IH</sub>	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
			10	7.0	—	7.0	5.50	—	7.0	—	
			15	11	—	11	8.25	—	11	—	
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source I <sub>OH</sub>	5.0	- 3.0	—	- 2.4	- 4.2	—	- 1.7	—	mAdc	
		5.0	- 0.64	—	- 0.51	- 0.88	—	- 0.36	—		
		10	- 1.6	—	- 1.3	- 2.25	—	- 0.9	—		
		15	- 4.2	—	- 3.4	- 8.8	—	- 2.4	—		
	Sink (V <sub>OL</sub> = 0.4 Vdc) (V <sub>OL</sub> = 0.5 Vdc) (V <sub>OL</sub> = 1.5 Vdc)	I <sub>OL</sub>	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
			10	1.6	—	1.3	2.25	—	0.9	—	
15	4.2	—	3.4	8.8	—	2.4	—	—			
Input Current	I <sub>in</sub>	15	—	±0.1	—	±0.00001	±0.1	—	±1.0	μAdc	
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	—	—	—	—	5.0	7.5	—	—	pF	
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0	—	5.0	—	0.005	5.0	—	150	μAdc	
		10	—	10	—	0.010	10	—	300		
		15	—	20	—	0.015	20	—	600		
Total Supply Current**† (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	I <sub>T</sub>	5.0 10 15	I <sub>T</sub> = (0.85 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (1.70 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (2.60 μA/kHz) f + I <sub>DD</sub>						μAdc		

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

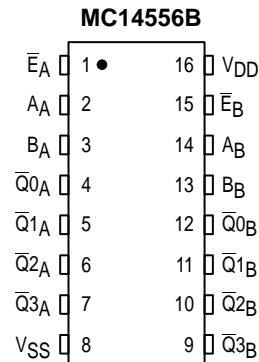
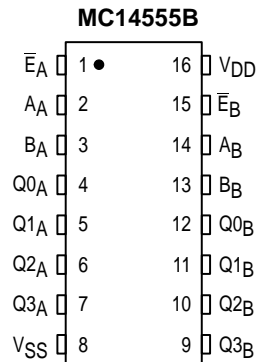
\*\*The formulas given are for the typical characteristics only at 25°C.

†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.002.

**PIN ASSIGNMENTS**

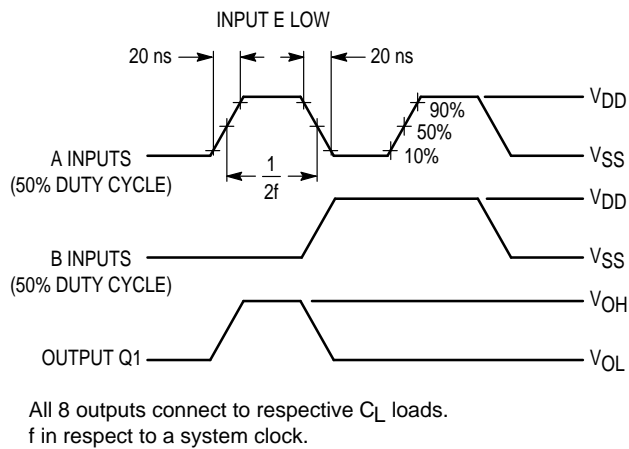


**SWITCHING CHARACTERISTICS\*** ( $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$ )

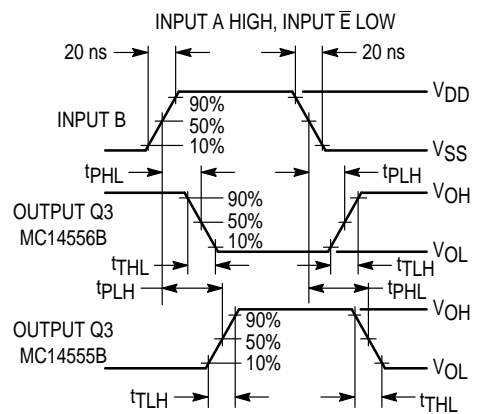
Characteristic	Symbol	V <sub>DD</sub>	Min	Typ #	Max	Unit
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	$t_{TLH}, t_{THL}$	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time — A, B to Output $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 135 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 62 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 45 \text{ ns}$	$t_{PLH}, t_{PHL}$	5.0 10 15	— — —	220 95 70	440 190 140	ns
Propagation Delay Time — E to Output $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 115 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 52 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 40 \text{ ns}$	$t_{PLH}, t_{PHL}$	5.0 10 15	— — —	200 85 65	400 170 130	ns

\* The formulas given are for the typical characteristics only at 25°C.

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

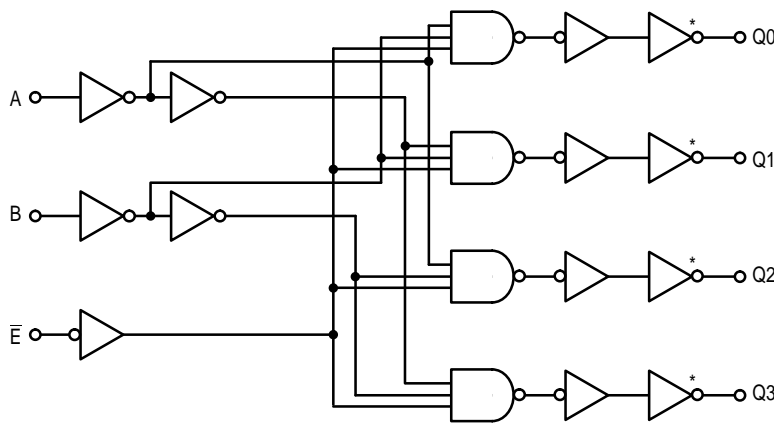


**Figure 1. Dynamic Power Dissipation Signal Waveforms**



**Figure 2. Dynamic Signal Waveforms**

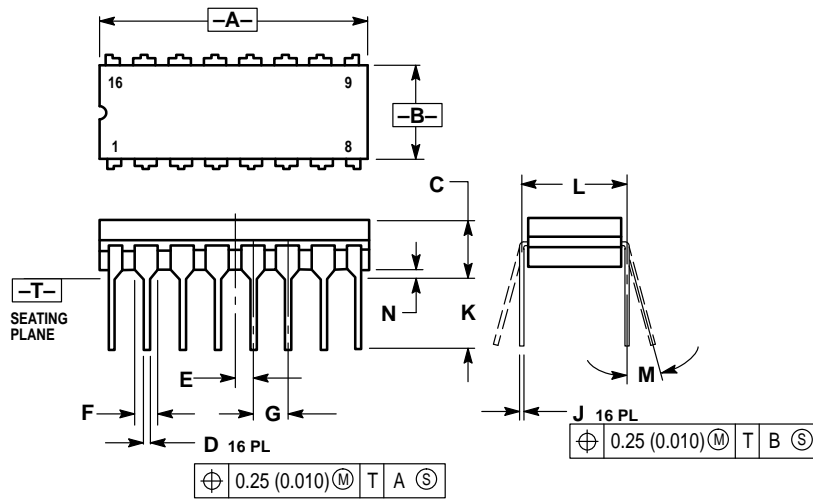
**LOGIC DIAGRAM**  
(1/2 of Dual)



\* Eliminated for MC14555B

## OUTLINE DIMENSIONS

### L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE V

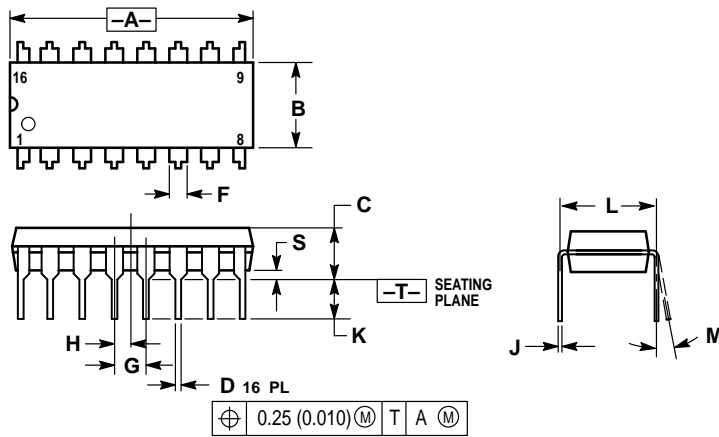


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

### P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



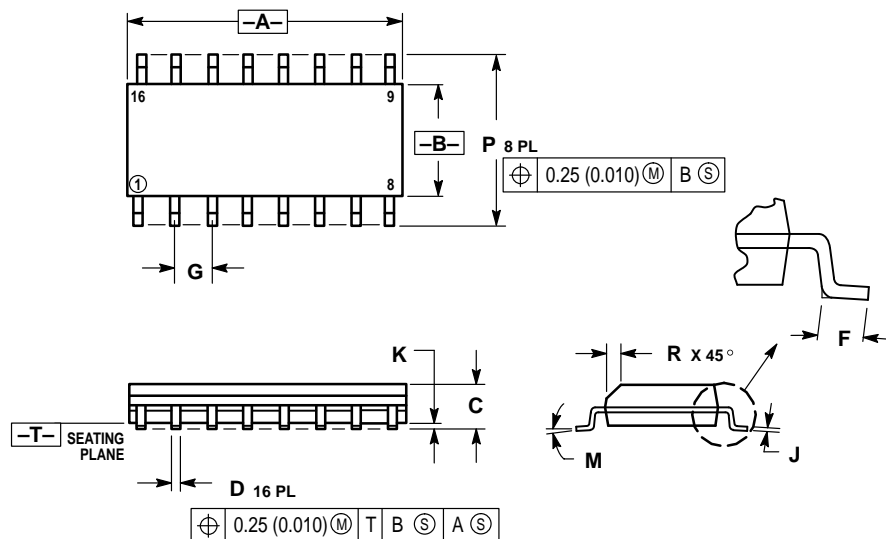
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

## OUTLINE DIMENSIONS

### D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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**MFAX:** RMFAX0@email.sps.mot.com – TOUCHTONE 602-244-6609  
**INTERNET:** <http://Design-NET.com>

**JAPAN:** Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, 6F Seibu-Butsuryu-Center,  
3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-81-3521-8315

**ASIA/PACIFIC:** Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park,  
51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298



MC14555B/D

